

KOBE STEEL's Tin Plating Copper Alloy Strips for Terminals and Connectors.

Tin Plating Types		Characteristic	Plating Compositions		Performance			
			Ni under Plating	Tin Plating	Reduction of Insertion Force Frictional Properties	Heat Reliability Contact Resistance	Solder Wet-ability	Fretting Characteristics
New Reflow Tin Plating	Standard	Lower Insertion Force	Non	0.6~1.3μm	◎ Excellent Less 50% than Reflow tin plating	○~△ Good	△ a little Good	○ Better
	Type S	Lower Insertion Force Better Heat Reliability	0.1~0.8μm	0.6~1.3μm	◎ Excellent Less 50% than Reflow tin plating	◎ Excellent	△ a little Good	○ Better
	Type S for Printed Circuit Board connector	Lower Insertion Force Better Solder Wet-ability	0.1~0.8μm	0.6~1.3μm	○ Better Less 25% than Reflow tin plating	◎ Excellent	○ Better	-
TN Plating		Lower Insertion Force	0.1~0.8μm	0.4~0.8μm	○ Better Less 25% than Reflow tin plating	◎ Excellent	△ a little Good	○~△ Good
TQ Plating		Better Heat Reliability Better Solder Wet-ability	0.1~0.8μm	1.0~2.0μm	-	◎ Excellent	○ Better	○~△ Good
Reflow Tin Plating			Non	0.8~2.0μm	× inferior	○ Better	○ Better	○~△ Good
Electrical Brightness Tin Plating			Non	0.8~2.0μm	△ a little Good Less 15% than Reflow tin plating	○ Better	△ a little Good	○~△ Good